

IN THE CLAIMS:

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS:

1 1. (original): A device comprising:
2 a tip of a bonding tool having a dissipative material for use in wire bonding
3 machines for connecting leads to integrated circuit bonding pads, wherein the tip has a
4 static discharge time between 0.1 and 0.5 seconds.

1 2. (original): A device comprising:
2 a bonding tool tip having an electrically dissipative ceramic for use in capillary
3 wedge-type wire bonding machines for connecting leads to integrated circuit bonding
4 pads.

1 3. (original): A method of using a bonding tool tip, comprising:
2 providing an electrically dissipative bonding tool tip;
3 bonding a material to a device;
4 allowing an essentially smooth current to dissipate to the device, the current
5 being low enough so as not to damage said device being bonded and

6 high enough to avoid a build up of charge that could discharge to the device being
7 bonded and damage the device being bonded.

1 4. (new): A device comprising:
2 a tip having a dissipative material for use in wire bonding machines for
3 connecting leads to integrated circuit bonding pads, wherein said dissipative material
4 has a resistance in the range of 5×10^5 to 10^{12} ohms.

1 5. (new): The device of claim 4 wherein the range of 5×10^5 to 10^{12} ohms of the
2 resistance is limited to 10^5 to 10^{12} ohms.